

In the claims:

Please amend the claims as follows:

14. (Currently amended) An encapsulated circuit comprising
a substrate having two faces and perimeter sides around the faces,
a circuit formed on the substrate,
conductive pads formed on a portion of one of the faces near one of the sides and
connected to the circuit, and

an integrally formed encapsulating mass which encapsulates all of the one face
except in the region of the pads, all of the other face except in a region opposite to the
region of the pads, and all of the sides except the one side in the region of the pads.

15. (Original) The encapsulated circuit of claim 14, wherein the circuit includes
electronic components mounted on both faces of the substrate and encapsulated in the
encapsulating mass.

16. (Original) The encapsulated circuit of claim 15, wherein the conductive pads are
formed on portions of the one face near the sides and the encapsulating mass encapsulates
all of the one face except in the regions of the pads.

17. (Original) The encapsulated circuit of claim 16, wherein the conductive pads are
formed on a portion of the other face near one of the sides and the encapsulating mass
encapsulated all of the other face except the region of the pads.

18. (Original) The encapsulated circuit of claim 17, wherein the conductive pads are
formed on portions of the other face near the sides and the encapsulating mass
encapsulated all of the other face except the regions of the pads.